

30V N-Channel NexFET™ Power MOSFET

Check for Samples: [CSD17303Q5](#)

FEATURES

- Optimized for 5V Gate Drive
- Ultralow Q_g and Q_{gd}
- Low Thermal Resistance
- Avalanche Rated
- Pb Free Terminal Plating
- RoHS Compliant
- Halogen Free
- SON 5-mm × 6-mm Plastic Package

APPLICATIONS

- Notebook Point-of-Load
- Point-of-Load Synchronous Buck in Networking, Telecom and Computing Systems
- Optimized for Synchronous FET Applications

DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications, and optimized for 5V gate drive applications.

PRODUCT SUMMARY

V_{DS}	Drain to Source Voltage	30	V
Q_g	Gate Charge Total (4.5V)	18	nC
Q_{gd}	Gate Charge Gate to Drain	4	nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 3V$	2.7 mΩ
		$V_{GS} = 4.5V$	2 mΩ
		$V_{GS} = 8V$	1.7 mΩ
$V_{GS(th)}$	Threshold Voltage	1.1	V

ORDERING INFORMATION

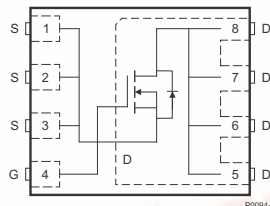
Device	Package	Media	Qty	Ship
CSD17303Q5	SON 5-mm × 6-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

ABSOLUTE MAXIMUM RATINGS

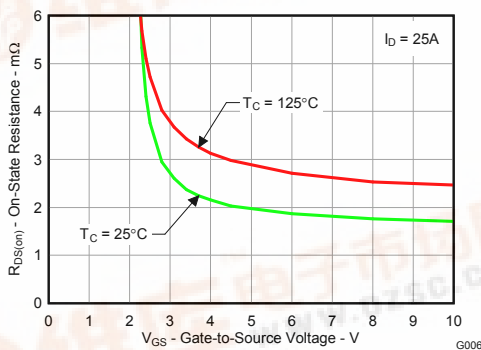
$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	+10 / -8	V
I_D	Continuous Drain Current, $T_C = 25^\circ\text{C}$	100	A
	Continuous Drain Current ⁽¹⁾	32	A
I_{DM}	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ ⁽²⁾	200	A
P_D	Power Dissipation ⁽¹⁾	3.2	W
T_J , T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
E_{AS}	Avalanche Energy, single pulse $I_D = 103A$, $L = 0.1mH$, $R_G = 25\Omega$	530	mJ

- (1) $R_{\theta JA} = 39^\circ\text{C/W}$ on 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52-mm) thick FR4 PCB.
 (2) Pulse duration $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

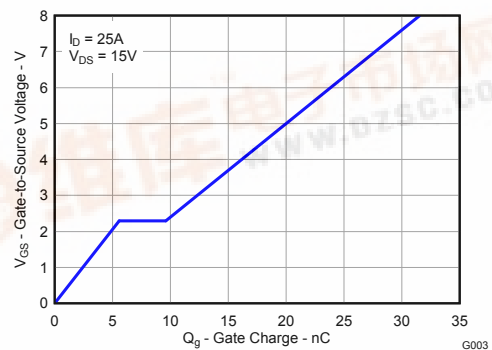
Top View



$R_{DS(on)}$ vs V_{GS}



GATE CHARGE



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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

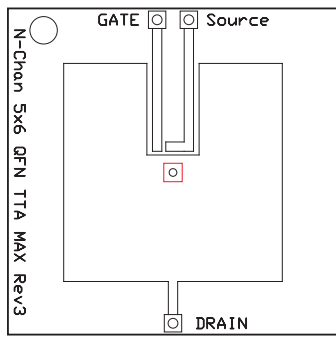
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
BV _{DSS}	Drain to Source Voltage	V _{GS} = 0V, I _D = 250μA	30			V
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 24V	1			μA
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = +10/−8V	100			nA
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	0.9	1.1	1.6	V
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 3V, I _D = 25A	2.7		3.7	mΩ
		V _{GS} = 4.5V, I _D = 25A	2		2.6	mΩ
		V _{GS} = 8V, I _D = 25A	1.7		2.4	mΩ
g _{fs}	Transconductance	V _{DS} = 15V, I _D = 25A	114			S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	2630	3420	pF	
C _{oss}	Output Capacitance		1440	1870	pF	
C _{rss}	Reverse Transfer Capacitance		83	108	pF	
R _G	Series Gate Resistance		1.4	2.8	Ω	
Q _g	Gate Charge Total (4.5V)	V _{DS} = 15V, I _{DS} = 25A	18	23	nC	
Q _{gd}	Gate Charge Gate to Drain		4	nC		
Q _{gs}	Gate Charge Gate to Source		5.6	nC		
Q _{g(th)}	Gate Charge at V _{th}		3	nC		
Q _{oss}	Output Charge	V _{DS} = 13.7V, V _{GS} = 0V	34	nC		
t _{d(on)}	Turn On Delay Time	V _{DS} = 15V, V _{GS} = 4.5V, I _{DS} = 25A, R _G = 2Ω	11.4	ns		
t _r	Rise Time		16	ns		
t _{d(off)}	Turn Off Delay Time		27	ns		
t _f	Fall Time		10.4	ns		
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _{SD} = 25A, V _{GS} = 0V	0.8	1	V	
Q _{rr}	Reverse Recovery Charge	V _{DD} = 13.7V, I _F = 25A, di/dt = 300A/μs	50	nC		
t _{rr}	Reverse Recovery Time		33	ns		

THERMAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

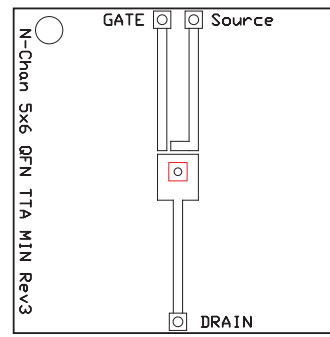
PARAMETER		MIN	TYP	MAX	UNIT
R _{θJC}	Thermal Resistance Junction to Case ⁽¹⁾			1.1	°C/W
R _{θJA}	Thermal Resistance Junction to Ambient ⁽¹⁾⁽²⁾			49	°C/W

- (1) R_{θJC} is determined with the device mounted on a 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch × 1.5-inch (3.81-cm × 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB. R_{θJC} is specified by design, whereas R_{θJA} is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.



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Max $R_{\theta JA} = 49^{\circ}\text{C/W}$
when mounted on
1 inch² (6.45 cm²) of
2-oz. (0.071-mm thick)
Cu.

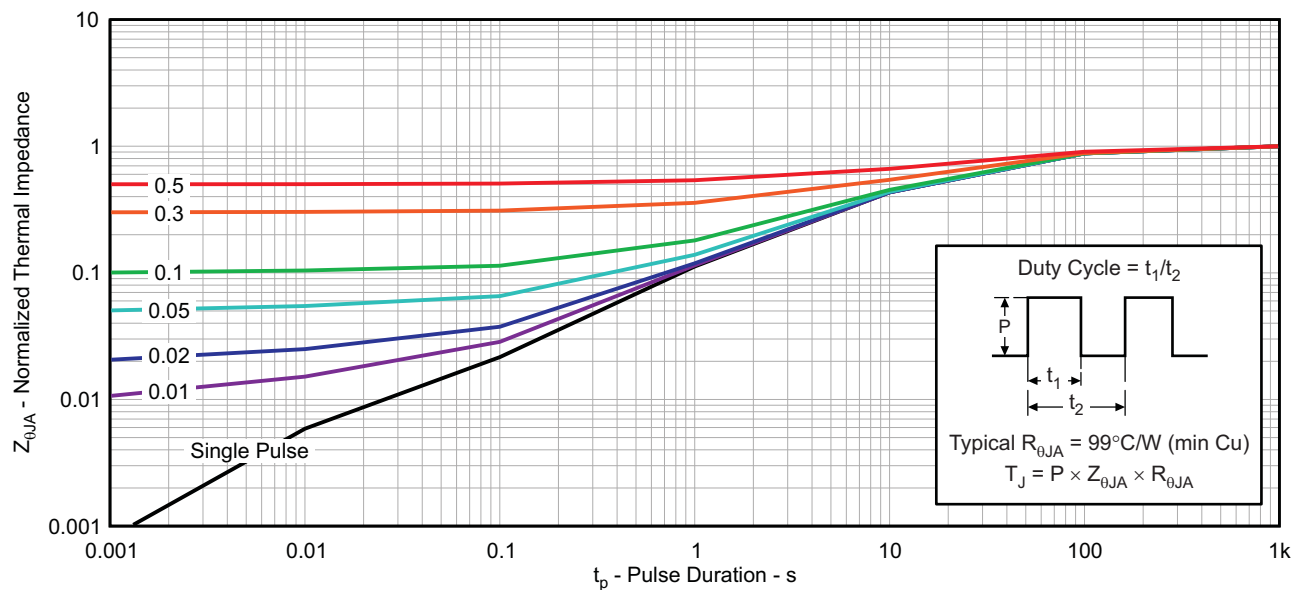


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Max $R_{\theta JA} = 124^{\circ}\text{C/W}$
when mounted on
minimum pad area of
2-oz. (0.071-mm thick)
Cu.

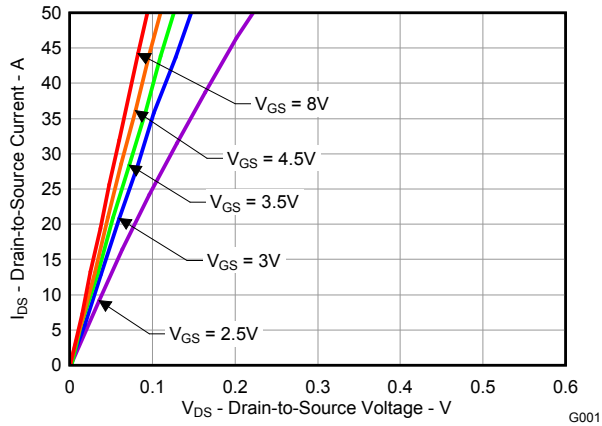
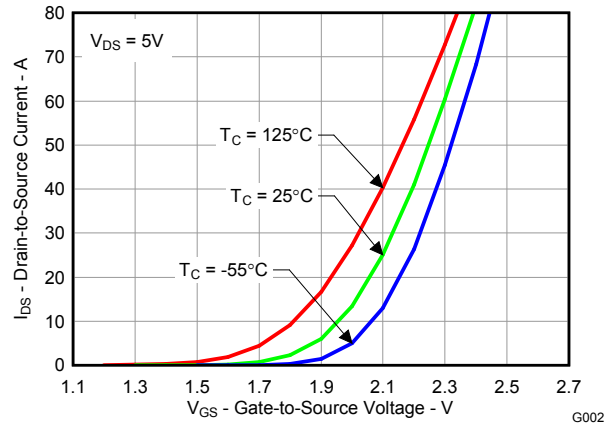
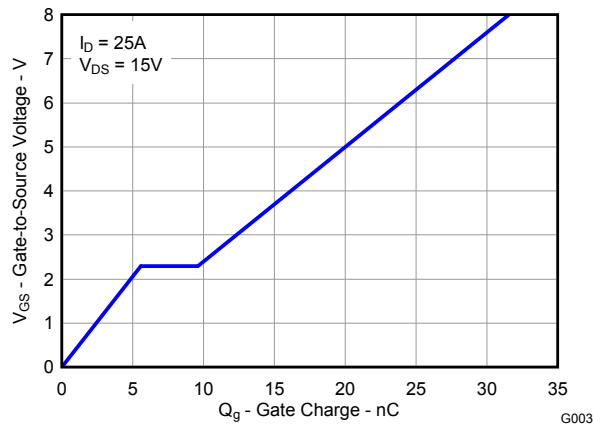
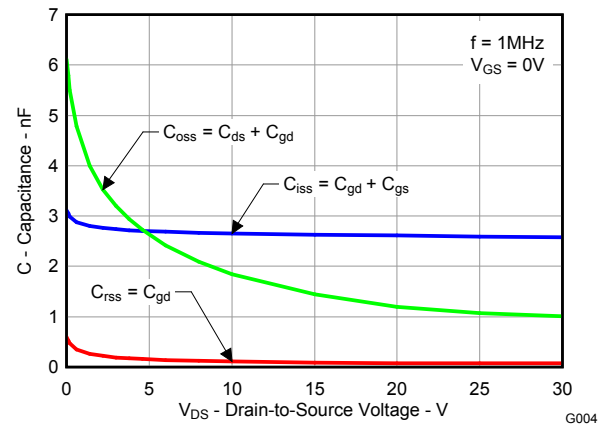
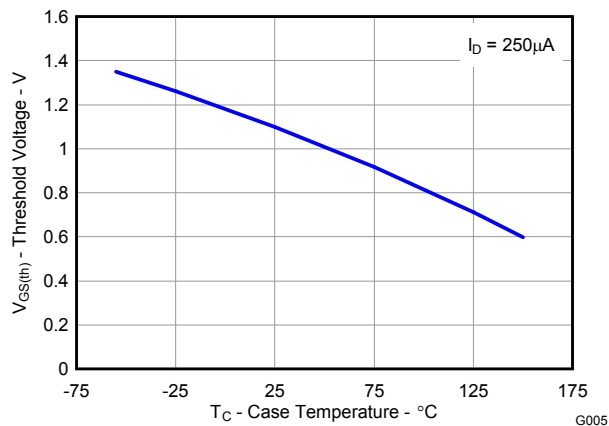
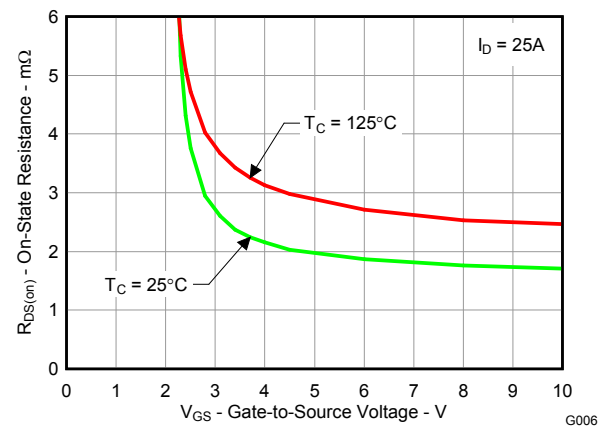
TYPICAL MOSFET CHARACTERISTICS

$T_A = 25^{\circ}\text{C}$, unless otherwise specified



G012

Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued) $T_A = 25^\circ\text{C}$, unless otherwise specified**Figure 2. Saturation Characteristics****Figure 3. Transfer Characteristics****Figure 4. Gate Charge****Figure 5. Capacitance****Figure 6. Threshold Voltage vs. Temperature****Figure 7. On-State Resistance vs. Gate-to-Source Voltage**

TYPICAL MOSFET CHARACTERISTICS (continued)

$T_A = 25^\circ\text{C}$, unless otherwise specified

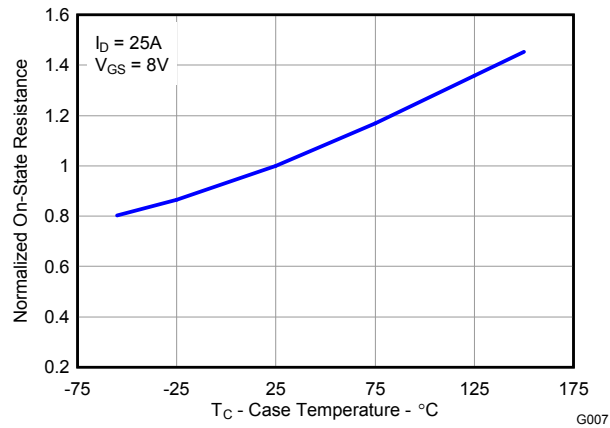


Figure 8. Normalized On-State Resistance vs. Temperature

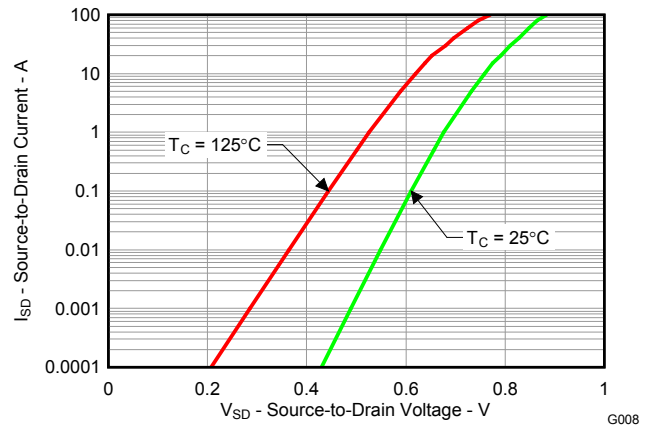


Figure 9. Typical Diode Forward Voltage

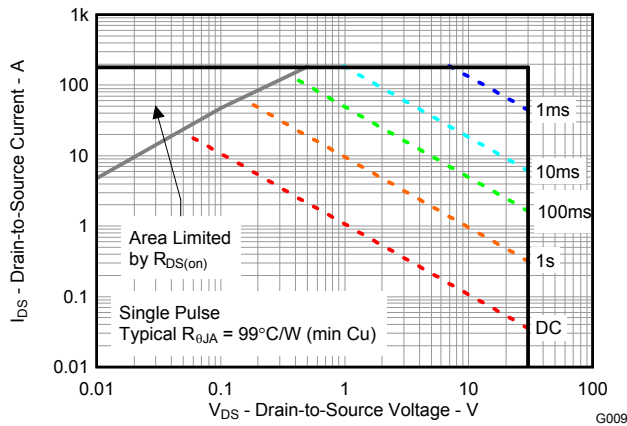


Figure 10. Maximum Safe Operating Area

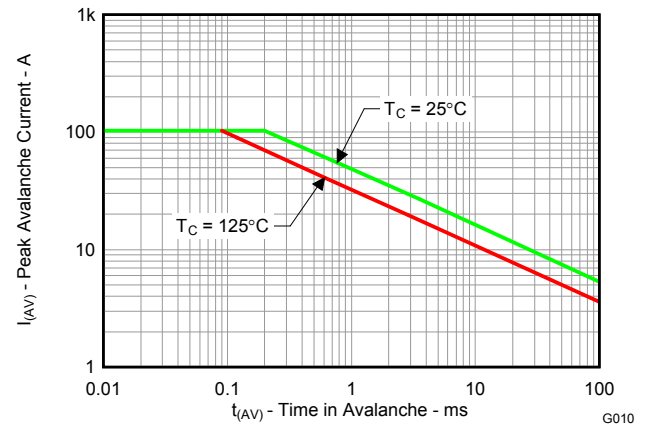


Figure 11. Single Pulse Unclamped Inductive Switching

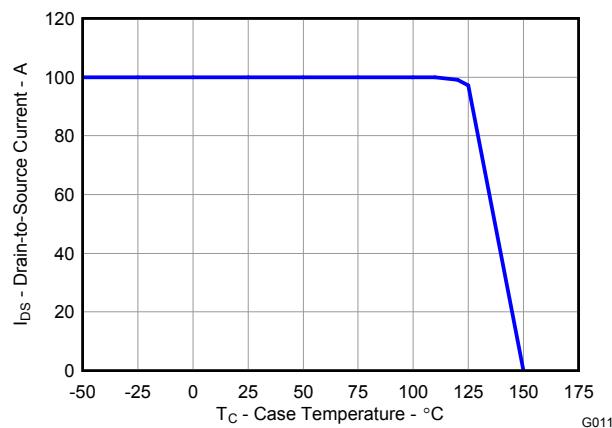
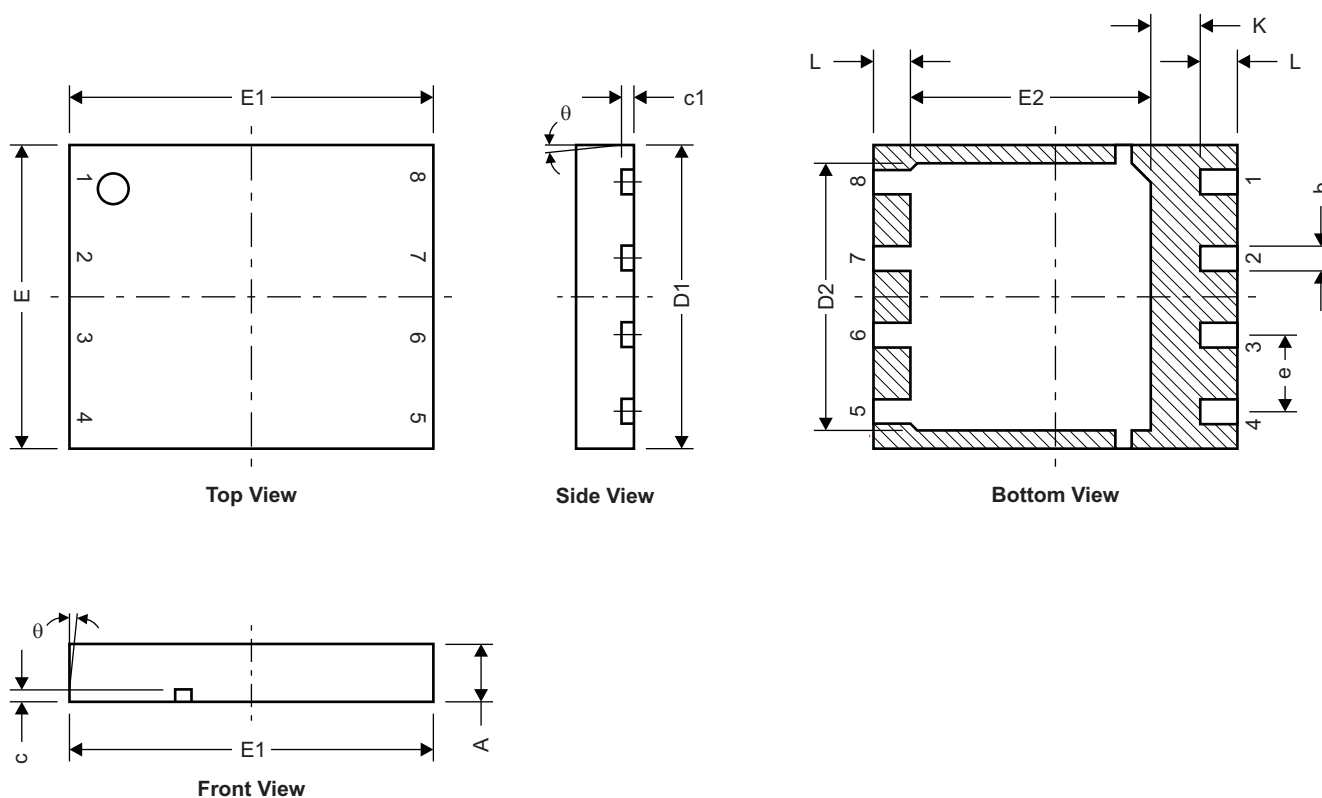


Figure 12. Maximum Drain Current vs. Temperature

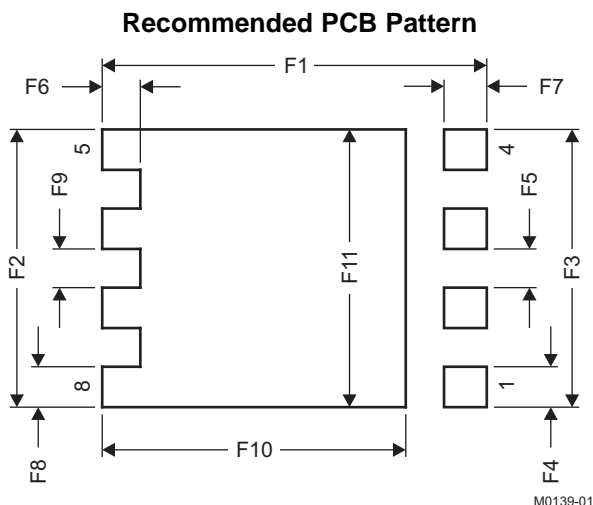
MECHANICAL DATA

Q5 Package Dimensions



M0140-01

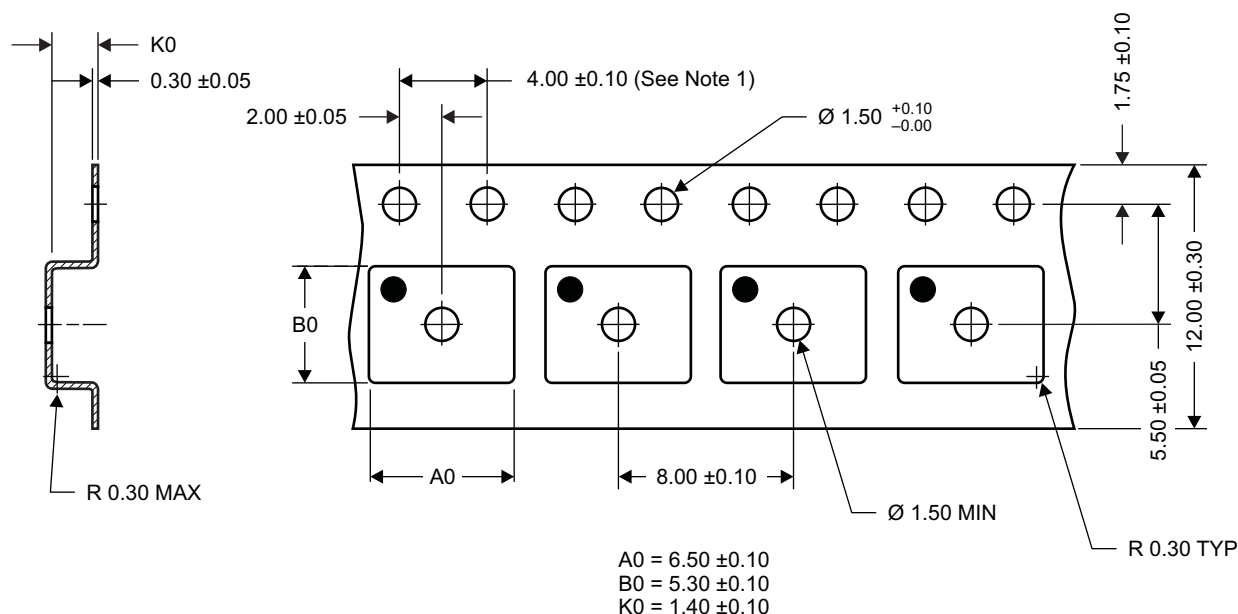
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.950	1.050	0.037	0.039
b	0.360	0.460	0.014	0.018
c	0.150	0.250	0.006	0.010
c1	0.150	0.250	0.006	0.010
D1	4.900	5.100	0.193	0.201
D2	4.320	4.520	0.170	0.178
E	4.900	5.100	0.193	0.201
E1	5.900	6.100	0.232	0.240
E2	3.920	4.12	0.154	0.162
e	1.27 TYP		0.050	
K	0.760		0.030	
L	0.510	0.710	0.020	0.028
θ	0.00			



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F1	6.205	6.305	0.244	0.248
F2	4.460	4.560	0.176	0.180
F3	4.460	4.560	0.176	0.180
F4	0.650	0.700	0.026	0.028
F5	0.620	0.670	0.024	0.026
F6	0.630	0.680	0.025	0.027
F7	0.700	0.800	0.028	0.031
F8	0.650	0.700	0.026	0.028
F9	0.620	0.670	0.024	0.026
F10	4.900	5.000	0.193	0.197
F11	4.460	4.560	0.176	0.180

For recommended circuit layout for PCB designs, see application note [SLPA005](#) – *Reducing Ringing Through PCB Layout Techniques*.

Q5 Tape and Reel Information



Notes:

- 10-sprocket hole-pitch cumulative tolerance ± 0.2
- Camber not to exceed 1mm in 100mm, noncumulative over 250mm
- Material: black static-dissipative polystyrene
- All dimensions are in mm (unless otherwise specified)
- Thickness: 0.30 ± 0.05 mm
- MSL1 260°C (IR and convection) PbF reflow compatible

[查询 CSD17303Q5 供应商](#)

REVISION HISTORY

Changes from Original (January 2010) to Revision A	Page
<ul style="list-style-type: none">Changed the Abs Max Ratings table, Avalanche Energy, single pulse From: $I_D = 85A$, $L = 0.1mH$, $R_G = 25\Omega$ Value = 361 To: $I_D = 103A$, $L = 0.1mH$, $R_G = 25\Omega$ Value = 530Changed Figure 11	<div>1</div> <div>5</div>
Changes from Revision A (February 2010) to Revision B	Page
<ul style="list-style-type: none">Deleted the Package Marking Information section	7

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